

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	949	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw titanium near10 tungsten) same (conduct\$5 barrier seed contact)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 12:27
S2	108	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw titanium near10 tungsten) same (conduct\$5 barrier seed contact)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 12:32
S3	39	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw titanium near10 tungsten) same (conduct\$5 barrier seed contact) and (chromium cr) and (nickel ni gold au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 12:44
S4	48	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw titanium near10 tungsten) same (conduct\$5 barrier seed contact) and seed near5 layer and (copper cu chromium cr) and (nickel ni gold au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 13:39
S5	48	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw titanium near10 tungsten) same (conduct\$5 barrier seed contact) and ((seed near5 layer) same (copper cu chromium cr)) and (nickel ni gold au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 13:49
S6	46	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw titanium near10 tungsten) same (barrier seed) and ((seed near5 layer) same (copper cu chromium cr)) and (nickel ni gold au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 14:34

S7	16	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw) same (barrier seed) and ((seed near5 layer) same (copper cu chromium cr)) and (nickel ni gold au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 13:50
S8	14	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw) with (barrier seed) and ((seed near5 layer) same (copper cu chromium cr)) and (nickel ni gold au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 13:54
S9	3	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw) with (barrier seed) and ((seed near5 layer) same (chromium cr)) and (nickel ni gold au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 13:54
S10	9	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw titanium near10 tungsten) same (barrier seed) and ((seed near5 layer) same (chromium cr)) and (nickel ni gold au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 13:58
S11	6	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) same (nickel ni gold au) and (tiw titanium near10 tungsten) same (barrier seed) and ((seed near5 layer) same (chromium cr))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 13:59
S12	18	("0057551" "0082913" "5486282" "5536388" "5620611" "6293457" "6355977" "6451627" "6534863").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 13:59
S13	0	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw titanium near10 tungsten) same (barrier seed) and ((seed near5 layer) same ((copper cu) near3 (chromium cr))) and (nickel ni gold au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 14:35

S14	0	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw titanium near10 tungsten) same (barrier seed) and ((seed near5 layer) same (cu near2 cr)) and (nickel ni gold au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 14:34
S15	0	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw titanium near10 tungsten) same (barrier seed) and (seed near5 layer) and (nickel ni gold au) and (cr/cu)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 14:36
S16	0	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw titanium near10 tungsten) same (barrier seed) and (seed near5 layer) and (nickel ni gold au) and ("cr/cu")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 14:37
S17	0	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw titanium near10 tungsten) and (nickel ni gold au) and ("cr/cu")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 14:37
S18	4	("205"/118,122-123,135-136,157. ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("cr/cu")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 11:25
S19	158	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("cr/cu")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 14:38
S20	28	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("cr/cu") and (tiw titanium near10 tungsten) and (nickel ni gold au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 14:46
S21	64	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("cr/cu" "cru") and (tiw titanium near10 tungsten) and (nickel ni gold au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 15:48

S22	0	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("cr/cu" "crcu") and (tiw titanium near10 tungsten) near10 electrode	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 15:49
S23	3	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("cr/cu" "crcu") and (tiw titanium near10 tungsten) near10 current	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 15:50
S24	0	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("cr/cu" "crcu") and (tiw titanium near10 tungsten) near10 coduct\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 15:51
S25	12	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("cr/cu" "crcu") and (tiw titanium near10 tungsten) near10 conduct\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 16:14
S26	103	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw titanium near10 tungsten) near10 current not S25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 16:16
S27	7	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (tiw titanium near10 tungsten) near10 current and solder not S25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 16:38
S28	5	("6605534").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/28 16:38
S29	9	("3791848" "4295924" "5256274" "5316974" "5629564" "6140234" "6168704" "6184138" "6379871").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/28 16:38
S30	9	("3791848" "4295924" "5256274" "5316974" "5629564" "6140234" "6168704" "6184138" "6379871").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/28 16:38

S31	277	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("cr/cu" "crcu" "cr-cu") and (nickel ni and gold au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 11:26
S32	183	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("cr/cu" "crcu" "cr-cu") and (nickel ni and gold au) and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 11:26
S33	118	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("cr/cu" "crcu" "cr-cu") and (nickel ni and gold au) and solder near5 (terminal connect\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 11:29
S34	92	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ("cr/cu" "crcu" "cr-cu") and (nickel ni) near5 (gold au) and solder near5 (terminal connect\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 11:30